LM9076Q 150mA Ultra-Low Quiescent Current LDO Regulator with Delayed Reset Output

Check for Samples: LM9076Q

FEATURES

- **AEC-Q100 Grade1 Qualified (-40°C to +125°C)**
- **Available with 5.0V or 3.3V Output Voltage**
- **Ultra Low Ground Pin Current, 25 µA Typical for 100 µA Load**
- **V_{OUT} Initial Accuracy of ±1.5%**
- **V_{OUT} Accurate to ±3% Over Load and Temperature Conditions**
- **Low Dropout Voltage, 200 mV Typical with 150 mA Load**
- **Low Off State Ground Pin Current for LM9076QBMA**
- **Delayed $\overline{\text{RESET}}$ Output Pin for Low V_{OUT} Detection**
- **+70V/-50V Voltage Transients**
- **Operational V_{IN} up to +40V**

DESCRIPTION

The LM9076Q is a ±3%, 150 mA logic controlled voltage regulator. The regulator features an active low delayed reset output flag which can be used to reset a microprocessor system at turn-ON and in the event that the regulator output voltage falls below a minimum value. An external capacitor programs a delay time interval before the reset output pin can return high.

Designed for automotive and industrial applications, the LM9076Q contains a variety of protection features such as thermal shutdown, input transient protection and a wide operating temperature range. The LM9076Q uses an PNP pass transistor which allows low drop-out voltage operation.

Typical Applications

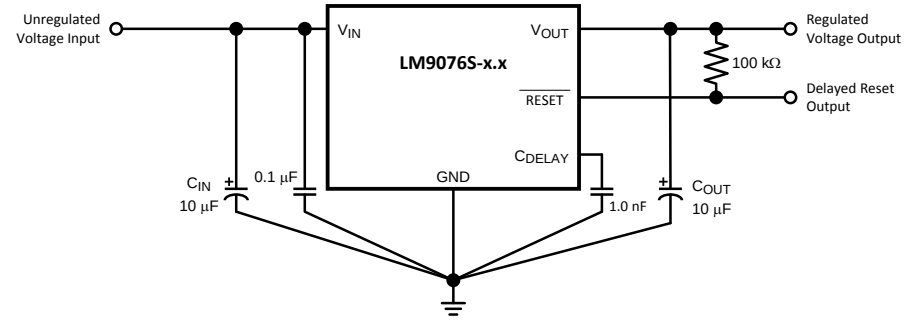


Figure 1. LM9076QS-x.x In 5 lead SFM package

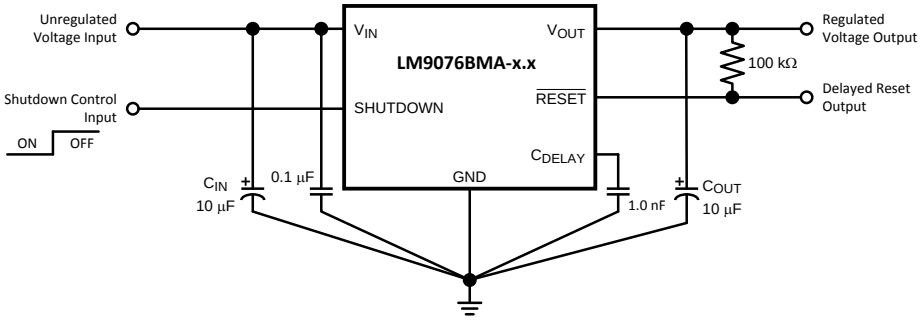


Figure 2. LM9076QBMA-x.x in 8 lead SOIC package

Connection Diagram

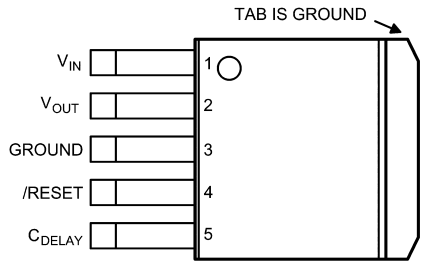


Figure 3. Top View
See SFM Package Number KTT0005B

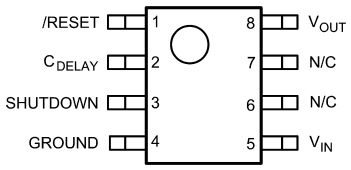


Figure 4. Top View
See SOIC Package Number D0008A

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

V_{IN}(DC)	-15V to +55V
V_{IN}(+Transient) t< 10ms, Duty Cycle <1%	+70V
V_{IN}(-Transient) t< 1ms, Duty Cycle <1%	-50V
SHUTDOWN Pin	-15V to +52V
$\overline{\text{RESET}}$ Pin	-0.3V to 20V
C_{DELAY} Pin	-0.3V to V_{OUT} +0.3V
Storage Temperature	-65°C to +150°C
Junction Temperature (T_J)	+175C
ESD, HBM, per AEC - Q100 - 002	+/-2 kV
ESD, MM, per AEC - Q100 - 003	+/-250V

(1) Absolute Maximum Ratings indicate the limits beyond which the device may cease to function, and/or damage to the device may occur.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

Operating Ratings (1)

V_{IN} Pin		5.35V to 40V
$V_{SHUTDOWN}$ Pin		0V to 40V
Junction Temperature		−40°C < T_J < +125°C
Thermal Resistance KTT0005B (2)	θja	75°C/W
	θjc	2.9°C/W
Thermal Resistance D0008A (2)	θja	156°C/W
	θjc	59°C/W

(1) Absolute Maximum Ratings indicate the limits beyond which the device may cease to function, and/or damage to the device may occur.
(2) Worst case (FREE AIR) per EIA/JESD51–3.

Electrical Characteristics for LM9076Q–3.3

The following specifications apply for V_{IN} = 14V; I_{LOAD} = 10 mA; T_J = +25C; C_{OUT} = 10 µF, 0.5Ω < ESR < 4.0Ω; unless otherwise specified. **Bold values indicate −40°C ≤ T_J ≤ +125°C**.(1) (2) Minimum and Maximum limits are specified through test, design or statistical correlation.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
LM9076Q–3.3 REGULATOR CHARACTERISTICS						
V_{OUT}	Output Voltage		3.251	3.30	3.349	V
		−20°C ≤ T_J ≤ 85°C 1 mA ≤ I_{LOAD} ≤ 150 mA	3.234	3.30	3.366	V
		1mA ≤ I_{LOAD} ≤ 150 mA	**3.201**	**3.30**	**3.399**	V
		V_{IN} = 60V, R_{LOAD} = 1 kΩ, t ≤ 40ms	2.970	3.30	3.630	V
	Output Voltage Off LM9076Q BMA only	$V_{SHUTDOWN}$ ≥ 2V, R_{LOAD} = 1 kΩ	–	0	250	mV
	Reverse Battery	V_{IN} = -15V, R_{LOAD} = 1 kΩ	−300	0	–	mV
ΔV_{OUT}	Line Regulation	9.0V ≤ V_{IN} ≤ 16V, I_{LOAD} = 10 mA	–	4	25	mV
		16V ≤ V_{IN} ≤ 40V, I_{LOAD} = 10 mA	–	17	35	mV
	Load Regulation	1 mA ≤ I_{LOAD} ≤ 150 mA	–	42	60	mV

(1) The regulated output voltage specification is not ensured for the entire range of V_{IN} and output loads. Device operational range is limited by the maximum junction temperature (T_J). The junction temperature is influenced by the ambient temperature (T_A), package selection, input voltage (V_{IN}), and the output load current. When operating with maximum load currents the input voltage and/or ambient temperature will be limited. When operating with maximum input voltage the load current and/or the ambient temperature will be limited.
(2) Pulse testing used maintain constant junction temperature (T_J).

Electrical Characteristics for LM9076Q–3.3 (continued)

The following specifications apply for V_{IN} = 14V; I_{LOAD} = 10 mA; T_J = +25C; C_{OUT} = 10 µF, 0.5Ω < ESR < 4.0Ω; unless otherwise specified. **Bold values indicate −40°C ≤ T_J ≤ +125°C.** (1) (2) Minimum and Maximum limits are specified through test, design or statistical correlation.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{DO}	Dropout Voltage	I_{LOAD} = 10 mA	–	30	50	mV
		I_{LOAD} = 50 mA	–	80	–	mV
		I_{LOAD} = 150 mA	–	150	250	mV
I_{GND}	Ground Pin Current	9V ≤ V_{IN} ≤ 16V, I_{LOAD} = 100 uA	–	25	45	µA
		9V ≤ V_{IN} ≤ 40V, I_{LOAD} = 10 mA	–	125	160	µA
		9V ≤ V_{IN} ≤ 40V, I_{LOAD} = 50 mA	–	0.6	–	mA
		9V ≤ V_{IN} ≤ 16V, I_{LOAD} = 150 mA	–	3.6	4.5	mA
I_{SC}	V_{OUT} Short Circuit Current	V_{IN} = 14V, R_{LOAD} = 1Ω	200	400	750	mA
PSRR	Ripple Rejection	V_{IN} = ($14V_{DC}$) + ($1V_{RMS}$ @ 120Hz) I_{LOAD} = 50 mA	50	60	–	dB
$\overline{\text{RESET}}$ PIN CHARACTERISTICS						
V_{OR}	Minimum V_{IN} for valid $\overline{\text{RESET}}$ Status		(3)–	1.3	2.0	V
V_{THR}	V_{OUT} Threshold for $\overline{\text{RESET}}$ Low	(3)	0.83	0.89	0.94	X V_{OUT} (Nom)
V_{OH}	$\overline{\text{RESET}}$ pin high voltage	External pull-up resistor to V_{OUT} = 100 kΩ	V_{OUT} X 0.90	V_{OUT} X 0.99	V_{OUT}	V
V_{OL}	$\overline{\text{RESET}}$ pin low voltage	C_{DELAY} < 4.0V, I_{SINK} = 250 µA	–	0.2	0.3	V
C_{DELAY} PIN CHARACTERISTICS						
I_{DELAY}	C_{DELAY} Charging Current	V_{IN} = 14V, V_{DELAY} = 0V	-0.70	-0.42	-0.25	uA
V_{OL}	C_{DELAY} pin low voltage	V_{OUT} < 4.0V, I_{SINK} = I_{DELAY}	–	0.100	–	V
t_{DELAY}	Reset Delay Time	V_{IN} = 14V, C_{DELAY} = 0.001 uF V_{OUT} rising from 0V, Δt from V_{OUT} > V_{OR} to $\overline{\text{RESET}}$ pin HIGH	4.7	7.8	13.2	ms

(3) Not Production tested, Specified by Design. Minimum, Typical, and/or Maximum values are provided for informational purposes only.

Electrical Characteristics for LM9076Q–5.0

The following specifications apply for V_{IN}= 14V; $V_{SHUTDOWN}$ = Open; I_{LOAD} = 10 mA; T_J = +25°C; C_{OUT} = 10 µF, 0.5Ω < ESR < 4.0Ω; unless otherwise specified. **Bold Values indicate −40°C ≤ T_J ≤ 125°C**. (1), (2) Minimum and Maximum limits are specified through test, design, or statistical correlation.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
LM9076Q–5.0 REGULATOR CHARACTERISTICS						
V_{OUT}	Output Voltage		4.925	5.00	5.075	V
		−20°C ≤ T_J ≤ 85°C 1 mA ≤ I_{LOAD} ≤ 150 mA	4.900	5.00	5.100	V
		1 mA ≤ I_{LOAD} ≤ 150 mA	**4.850**	**5.00**	**5.150**	V
		V_{IN} = 60V, R_{LOAD} = 1 kΩ, t ≤ 40ms	4.500	5.00	5.500	V
	Output Voltage Off LM9076Q BMA only	$V_{SHUTDOWN}$ ≥ 2V, R_{LOAD} = 1 kΩ	–	0	250	mV
	Reverse Battery	V_{IN} = -15V, R_{LOAD} = 1 kΩ	−300	0	–	mV
ΔV_{OUT}	Line Regulation	9.0V ≤ V_{IN} ≤ 16V, I_{LOAD} = 10 mA	–	4	25	mV
		16V ≤ V_{IN} ≤ 40V, I_{LOAD} = 10 mA	–	17	35	mV
	Load Regulation	1 mA ≤ I_{LOAD} ≤ 150 mA	–	42	60	mV
V_{DO}	Dropout Voltage	I_{LOAD} = 10 mA	–	30	50	mV
		I_{LOAD} = 50 mA	–	80	–	mV
		I_{LOAD} = 150 mA	–	150	250	mV
I_{GND}	Ground Pin Current	9V ≤ V_{IN} ≤ 16V, I_{LOAD} = 100 uA	–	25	45	µA
		9V ≤ V_{IN} ≤ 40V, I_{LOAD} = 10 mA	–	125	160	µA
		9V ≤ V_{IN} ≤ 40V, I_{LOAD} = 50 mA	–	0.6	–	mA
		9V ≤ V_{IN} ≤ 16V, I_{LOAD} = 150 mA	–	3.6	4.5	mA
	Ground Pin Current in Shutdown Mode	9V ≤ V_{IN} ≤ 40V, $V_{SHUTDOWN}$ = 2V	–	15	25	µA
I_{SC}	V_{OUT} Short Circuit Current	V_{IN} = 14V, R_{LOAD} = 1Ω	200	400	750	mA
PSRR	Ripple Rejection	V_{IN} = (14V_{DC}) + (1V_{RMS} @ 120Hz) I_{LOAD} = 50 mA	50	60	–	dB
$\overline{\text{RESET}}$ PIN CHARACTERISTICS						
V_{OR}	Minimum V_{IN} for valid $\overline{\text{RESET}}$ Status		(3)_	1.3	2.0	V
V_{THR}	V_{OUT} Threshold for $\overline{\text{RESET}}$ Low	(3)	0.83	0.89	0.94	X V_{OUT} (Nom)
V_{OH}	$\overline{\text{RESET}}$ pin high voltage	External pull-up resistor to V_{OUT} = 100 kΩ	V_{OUT} X 0.90	V_{OUT} X 0.99	V_{OUT}	V
V_{OL}	$\overline{\text{RESET}}$ pin low voltage	C_{DELAY} < 4.0V, I_{SINK} = 250 µA	–	0.2	0.3	V
C_{DELAY} PIN CHARACTERISTICS						
I_{DELAY}	C_{DELAY} Charging Current	V_{IN} = 14V, V_{DELAY} = 0V	-0.70	-0.42	-0.25	uA

(1) Pulse testing used maintain constant junction temperature (T_J).
(2) The regulated output voltage specification is not ensured for the entire range of V_{IN} and output loads. Device operational range is limited by the maximum junction temperature (T_J). The junction temperature is influenced by the ambient temperature (T_A), package selection, input voltage (V_{IN}), and the output load current. When operating with maximum load currents the input voltage and/or ambient temperature will be limited. When operating with maximum input voltage the load current and/or the ambient temperature will be limited.
(3) Not Production tested, Specified by Design. Minimum, Typical, and/or Maximum values are provided for informational purposes only.

Electrical Characteristics for LM9076Q–5.0 (continued)

The following specifications apply for V_{IN}= 14V; $V_{SHUTDOWN}$ = Open; I_{LOAD} = 10 mA; T_J = +25°C; C_{OUT} = 10 µF, 0.5Ω < ESR < 4.0Ω; unless otherwise specified. **Bold Values indicate −40°C ≤ T_J ≤ 125°C**. (1), (2) Minimum and Maximum limits are specified through test, design, or statistical correlation.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{OL}	C_{DELAY} pin low voltage	V_{OUT} < 4.0V, I_{SINK} = I_{DELAY}	–	0.100	–	V
t_{DELAY}	Reset Delay Time	V_{IN} = 14V, C_{DELAY} = 0.001 uF V_{OUT} rising from 0V, Δt from V_{OUT} > V_{OR} to $\overline{\text{RESET}}$ pin HIGH	7.1	11.9	20.0	ms
SHUTDOWN CONTROL LOGIC — LM9076QBMA-5.0 Only						
$V_{IL(SD)}$	SHUTDOWN Pin Low Threshold Voltage	$V_{SHUTDOWN}$ pin falling from 5.0V until V_{OUT} >4.5V (V_{OUT} = On)	1	1.5	–	V
$V_{IH(SD)}$	SHUTDOWN Pin High Threshold Voltage	$V_{SHUTDOWN}$ pin rising from 0V until V_{OUT} < 0.5V (V_{OUT} = Off)	–	1.5	2	V
$I_{IH(SD)}$	SHUTDOWN Pin High Bias Current	$V_{SHUTDOWN}$ = 40V	–	35	–	µA
		$V_{SHUTDOWN}$ = 5V	–	15	35	µA
		$V_{SHUTDOWN}$ = 2V	–	6	10	µA
$I_{IL(SD)}$	SHUTDOWN Pin Low Bias Current	$V_{SHUTDOWN}$ = 0V	–	0	–	µA

Typical Performance Characteristics

Output Capacitor ESR

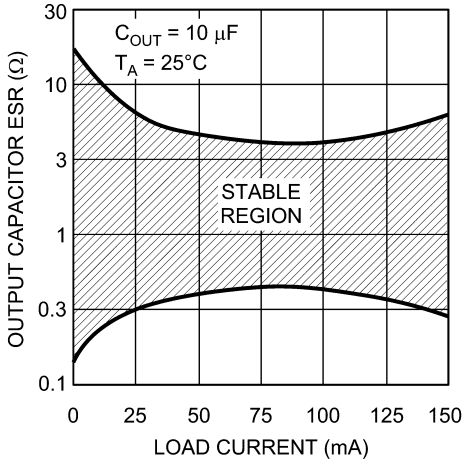


Figure 5.

Output Capacitor ESR

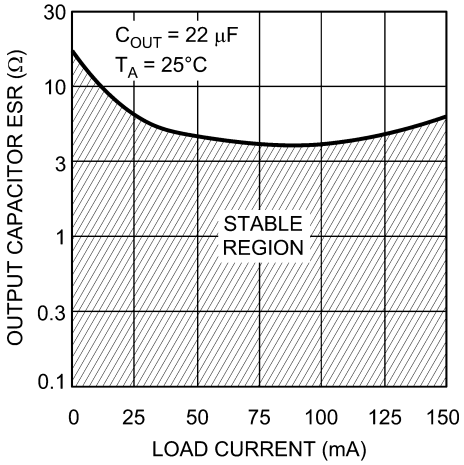


Figure 6.

Output Voltage vs Low Input Voltage

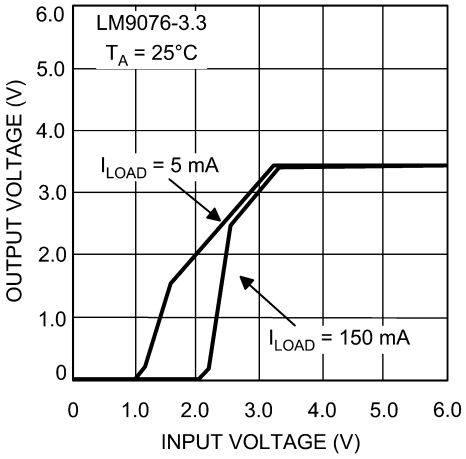


Figure 7.

Output Voltage vs Low Input Voltage

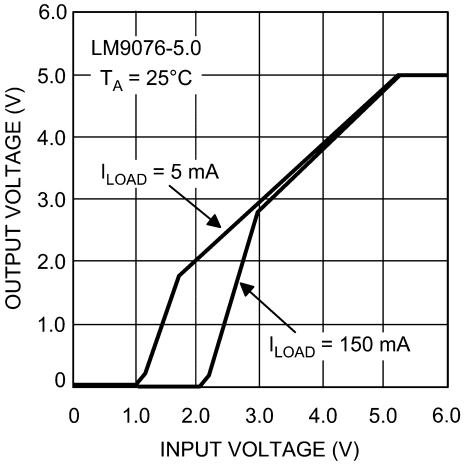


Figure 8.

Ground Pin Current vs Low Input Voltage

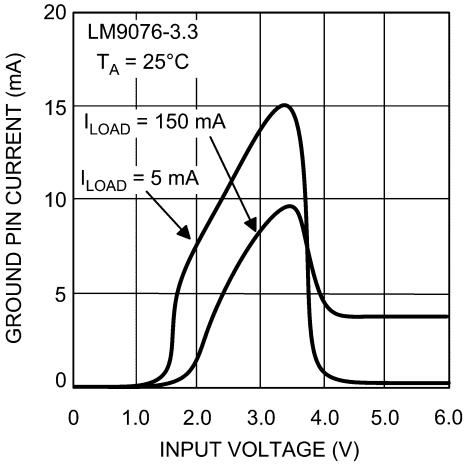


Figure 9.

Ground Pin Current vs Low Input Voltage

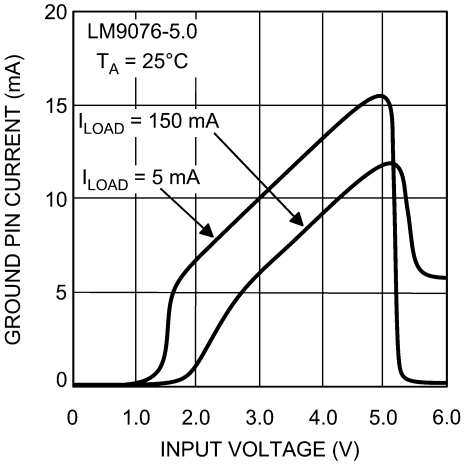


Figure 10.

Typical Performance Characteristics (continued)

Ground Pin Current vs Load Current

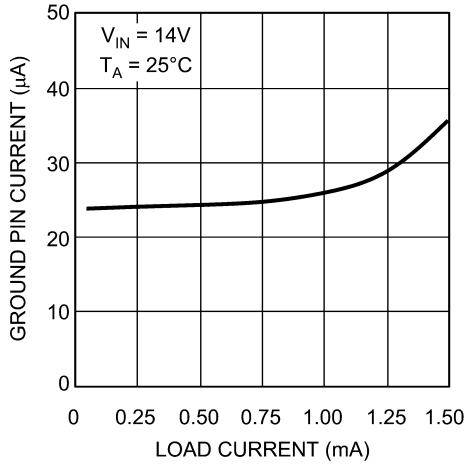


Figure 11.

Ground Pin Current vs Load Current

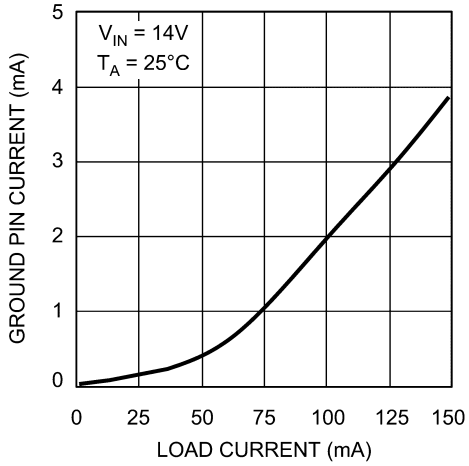


Figure 12.

Output Voltage vs Input Voltage

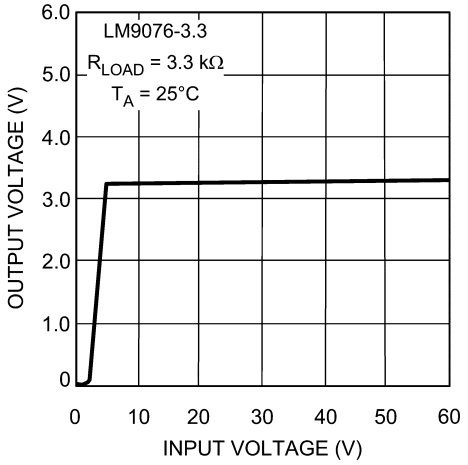


Figure 13.

Output Voltage vs Input Voltage

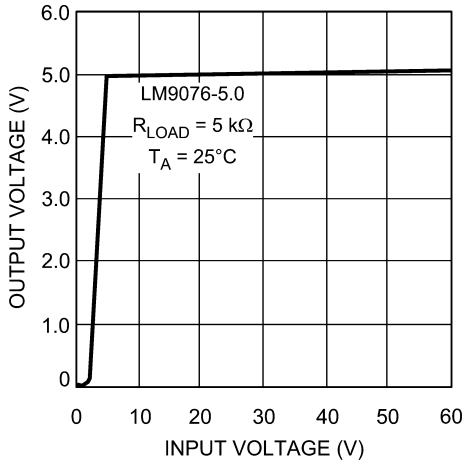


Figure 14.

Output Voltage vs Junction Temperature

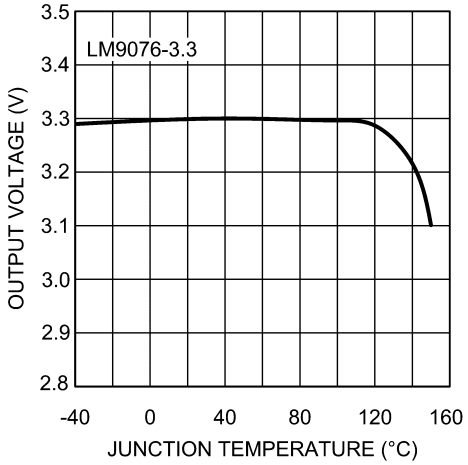


Figure 15.

Output Voltage vs Junction Temperature

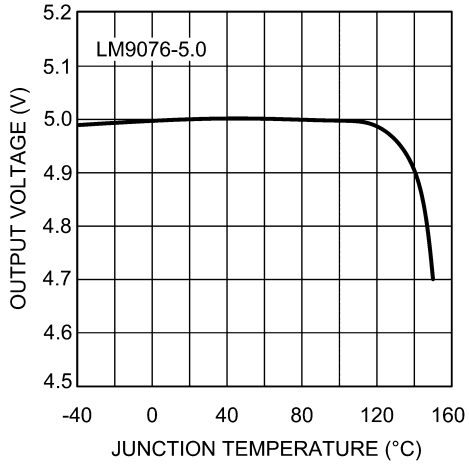


Figure 16.

Typical Performance Characteristics (continued)

Dropout Voltage vs Load Current

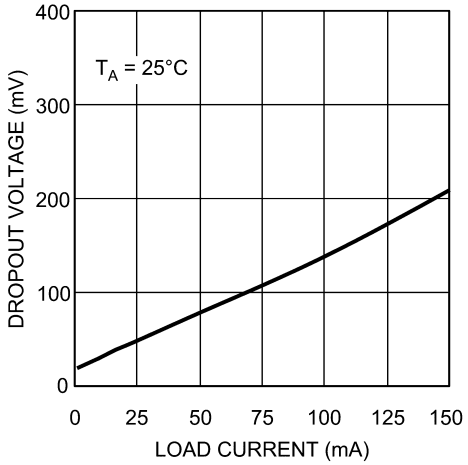


Figure 17.

Load Transient Response

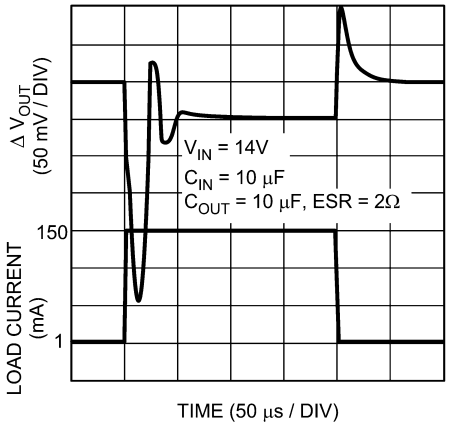


Figure 18.

Load Transient Response

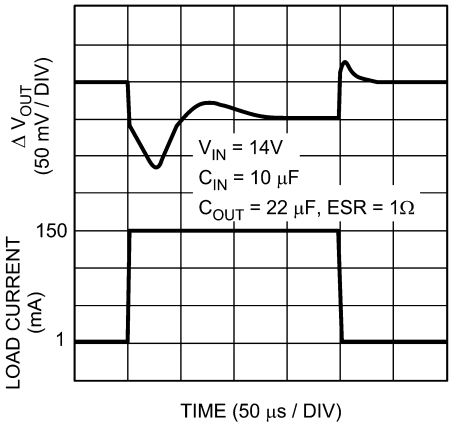


Figure 19.

Line Transient Response

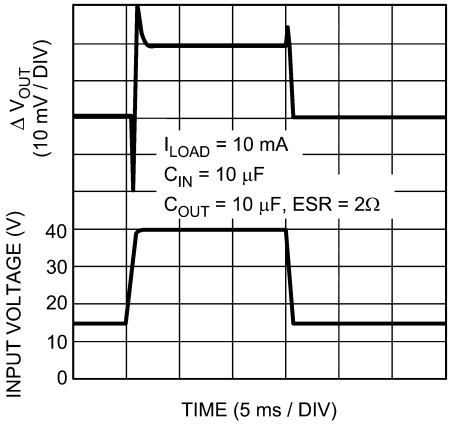


Figure 20.

Line Transient Response

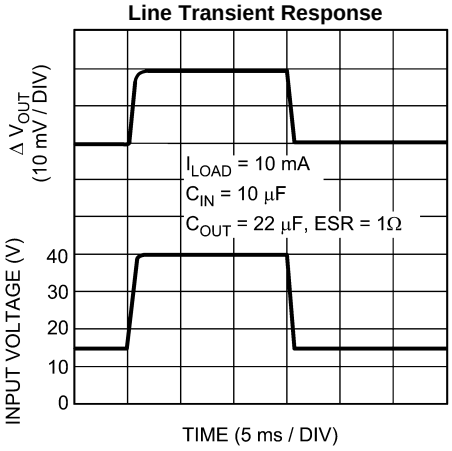


Figure 21.

Delayed Reset Time vs Vin Normalized to V_{IN} = 14V

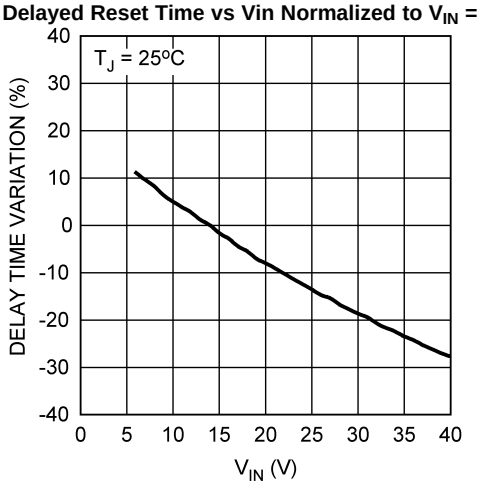


Figure 22.

Typical Performance Characteristics (continued)

Ripple Rejection

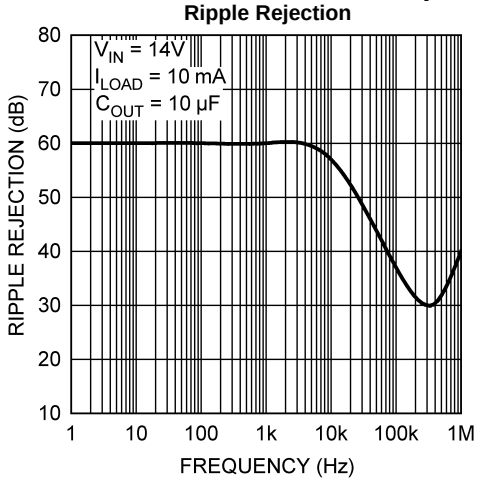


Figure 23.

APPLICATION INFORMATION

REGULATOR BASICS

The LM9076Q regulator is suitable for Automotive and Industrial applications where continuous connection to a battery supply is required (refer to the Typical Application circuit).

The pass element of the regulator is a PNP device which requires an output bypass capacitor for stability. The minimum bypass capacitance for the output is 10 µF (refer to ESR limitations). A 22 µF, or larger, output bypass capacitor is recommended for typical applications

INPUT CAPACITOR

The LM9076Q requires a low source impedance to maintain regulator stability because critical portions of the internal bias circuitry are connected to directly to V_{IN}. In general, a 10 µF electrolytic capacitor, located within two inches of the LM9076Q, is adequate for a majority of applications. Additionally, and at a minimum, a 0.1 µF ceramic capacitor should be located between the LM9076Q V_{IN} and Ground pin, and as close as is physically possible to the LM9076Q itself .

OUTPUT CAPACITOR

An output bypass capacitor is required for stability. This capacitance must be placed between the LM9076Q V_{OUT} pin and Ground pin, as close as is physically possible, using traces that are not part of the load current path.

The output capacitor must meet the requirements for minimum capacitance and also maintain the appropriate ESR value across the entire operating ambient temperature range. There is no limit to the maximum output capacitance as long as ESR is maintained.

The minimum bypass capacitance for the output is 10 µF (refer to ESR limitations). A 22 µF, or larger, output bypass capacitor is recommended for typical applications.

Solid tantalums capacitors are recommended as they generally maintain capacitance and ESR ratings over a wide temperature range. Ceramic capacitor types XR7 and XR5 may be used if a series resistor is added to simulate the minimum ESR requirement. See Figure 24.

Aluminum electrolytic capacitors are not recommended as they are subject to wide changes in capacitance and ESR across temperature.

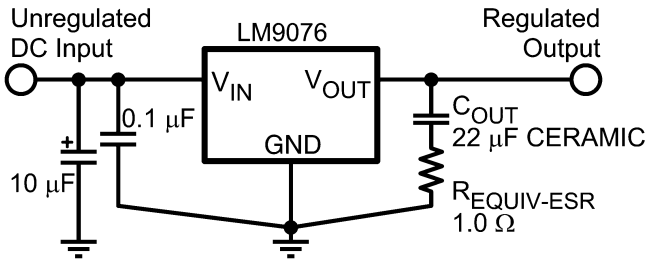


Figure 24. Using Low ESR Capacitors

DELAY CAPACITOR

The capacitor on the Delay pin must be a low leakage type since the charge current is minimal (420 nA typical) and the pin must fully charge to V_{OUT}. Ceramic, Mylar, and polystyrene capacitor types are generally recommended, although changes in capacitance values across temperature changes will have some effect on the delay timing.

Any leakage of the I_{DELAY} current, be it through the delay capacitor or any other path, will extend the delay time, possibly to the point that the Reset pin output does not go high.

SHUTDOWN PIN - LM9076QBMA ONLY

The basic On/Off control of the regulator is accomplished with the SHUTDOWN pin. By pulling the SHUTDOWN pin high the regulator output is switched Off. When the regulator is switched Off the load on the battery will be primarily due to the SHUTDOWN pin current.

When the SHUTDOWN pin is low, or left open, the regulator is switched On. When an unregulated supply, such as V BATTERY , is used to pull the SHUTDOWN pin high a series resistor in the range of 10KΩ to 50KΩ is recommended to provide reverse voltage transient protection of the SHUTDOWN pin. Adding a small capacitor (0.001uF typical) from the SHUTDOWN pin to Ground will add noise immunity to prevent accidental turn on due to noise on the supply line.

$\overline{\text{RESET}}$ FLAG

The $\overline{\text{RESET}}$ pin is an open collector output which requires an external pull-up resistor to develop the reset signal. The external pull-up resistor should be in the range of 10 kΩ to 200 kΩ.

At V_{IN} values of less than typically 2V the $\overline{\text{RESET}}$ pin voltage will be high. For V_{IN} values between typically 2V and approximately V_{OUT} + V_{BE} the $\overline{\text{RESET}}$ pin voltage will be low. For V_{IN} values greater than approximately V_{OUT} + V_{BE} the $\overline{\text{RESET}}$ pin voltage will be dependent on the status of the V_{OUT} pin voltage and the Delayed Reset circuitry. The value of V_{BE} is typically 600 mV at 25°C and will decrease approximately 2 mV for every 1°C increase in the junction temperature. During normal operation the $\overline{\text{RESET}}$ pin voltage will be high .

Any load condition that causes the V_{OUT} pin voltage to drop below typically 89% of normal will activate the Delayed Reset circuit and the $\overline{\text{RESET}}$ pin will go low for the duration of the delay time.

Any line condition that causes V_{IN} pin voltage to drop below typically V_{OUT} + V_{BE} will cause the $\overline{\text{RESET}}$ pin to go low without activating the Delayed Reset circuitry.

Excessive thermal dissipation will raise the junction temperature and could activate the Thermal Shutdown circuitry which, in turn, will cause the $\overline{\text{RESET}}$ pin to go low.

For the LM9076QBMA devices, pulling the SHUTDOWN pin high will turn off the output which, in turn, will cause the $\overline{\text{RESET}}$ pin to go low once the V_{OUT} voltage has decayed to a value that is less than typically 89% of normal. See Figure 25.

$\overline{\text{RESET}}$ DELAY TIME

When the regulator output is switched On, or after recovery from brief V_{OUT} fault condition, the $\overline{\text{RESET}}$ flag can be can be programmed to remain low for an additional delay time. This will give time for any system reference voltages, clock signals, etc., to stabilize before the micro-controller resumes normal operation.

This delay time is controlled by the capacitor value on the C_{DELAY} pin. During normal operation the C_{DELAY} capacitor is charged to near V_{OUT} . When a V_{OUT} fault causes the $\overline{\text{RESET}}$ pin to go low, the C_{DELAY} capacitor is quickly discharged to ground. When the V_{OUT} fault is removed, and V_{OUT} returns to the normal operating value, the C_{DELAY} capacitor begins charging at a typical constant 0.420 uA rate. When the voltage on the C_{DELAY} capacitor reaches the same potential as the V_{OUT} pin the $\overline{\text{RESET}}$ pin will be allowed to return high.

The typical $\overline{\text{RESET}}$ delay time can be calculated with the following formula:

$$t_{DELAY} = V_{OUT} \text{ X } (C_{DELAY} / I_{DELAY}) \quad (1)$$

For the LM9076Q–3.3 with a C_{DELAY} value of 0.001 uF and a I_{DELAY} value of 0.420 uA the typical $\overline{\text{RESET}}$ delay time is:

$$t_{DELAY} = 3.3V \times (0.001 \text{ uF} / 0.420 \text{ uA}) = 7.8 \text{ ms} \quad (2)$$

For the LM9076Q–5.0 with a C_{DELAY} value of 0.001 uF and a I_{DELAY} value of 0.420 uA the typical $\overline{\text{RESET}}$ delay time is:

$$t_{DELAY} = 5.0V \text{ X } (0.001uF / 0.420uA) = 11.9 \text{ ms} \quad (3)$$

THERMAL PROTECTION

Device operational range is limited by the maximum junction temperature (T_J). The junction temperature is influenced by the ambient temperature (T_A), package selection, input voltage (V_{IN}), and the output load current. When operating with maximum load currents the input voltage and/or ambient temperature will be limited. When operating with maximum input voltage the load current and/or the ambient temperature will be limited.

Even though the LM9076Q is equipped with circuitry to protect itself from excessive thermal dissipation, it is not recommended that the LM9076Q be operated at, or near, the maximum recommended die junction temperature (T_J) as this may impair long term device reliability.

The thermal protection circuity monitors the temperature at the die level. When the die temperature exceeds typically 160°C the voltage regulator output will be switched off.

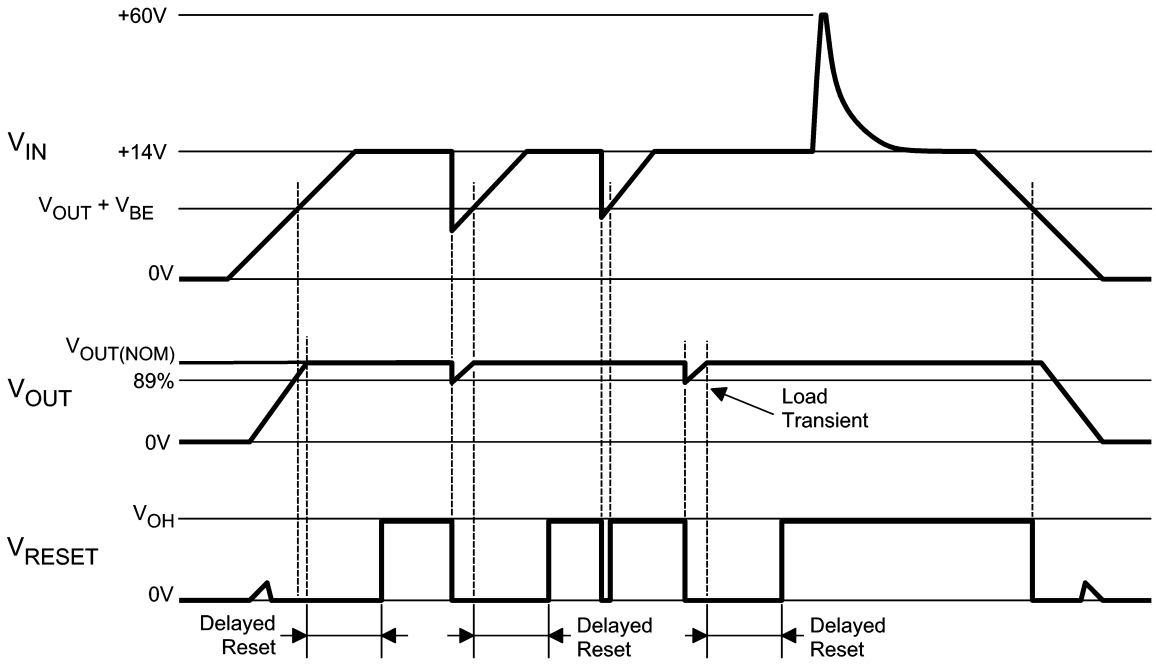


Figure 25. Typical $\overline{\text{Reset}}$ Pin Operational Waveforms

REVISION HISTORY

Changes from Revision A (March 2013) to Revision B	Page
• Changed layout of National Data Sheet to TI format	13

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM9076QBMA-3.3/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	9076B QMA3.3	Samples
LM9076QBMA-5.0/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	9076B QMA5.0	Samples
LM9076QBMAX-3.3/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	9076B QMA3.3	Samples
LM9076QBMAX-5.0/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	9076B QMA5.0	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

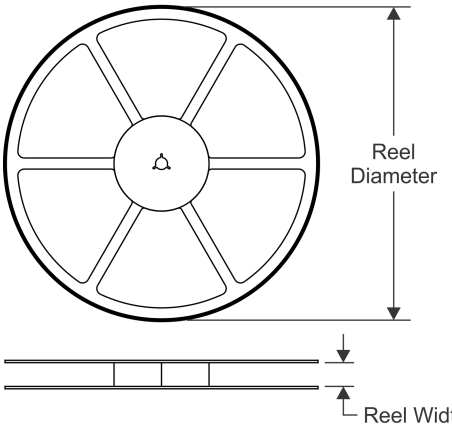
(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

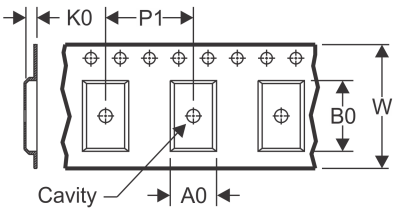
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

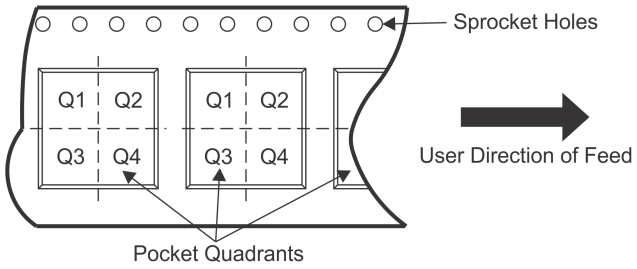


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

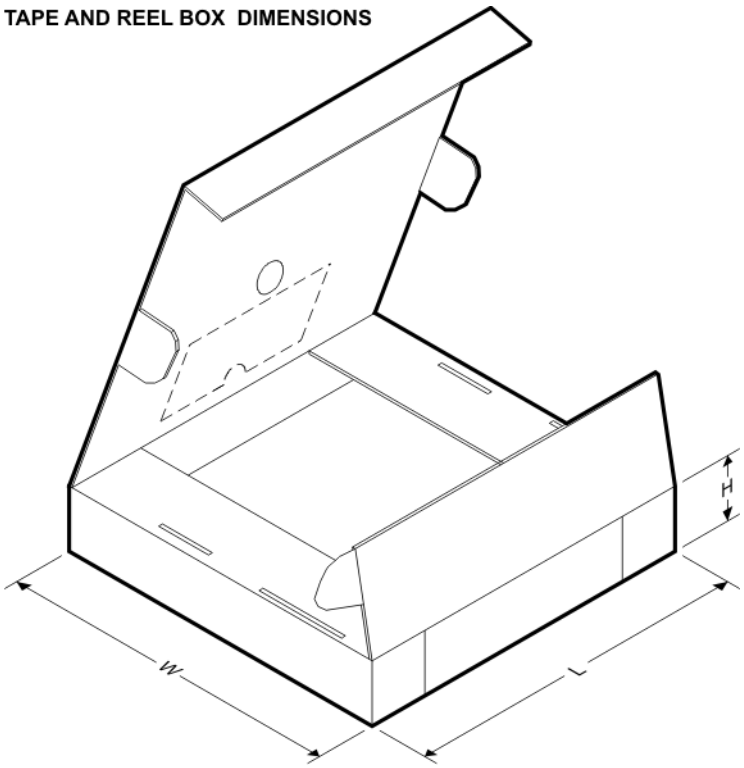
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM9076QBMAX-3.3/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM9076QBMAX-5.0/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

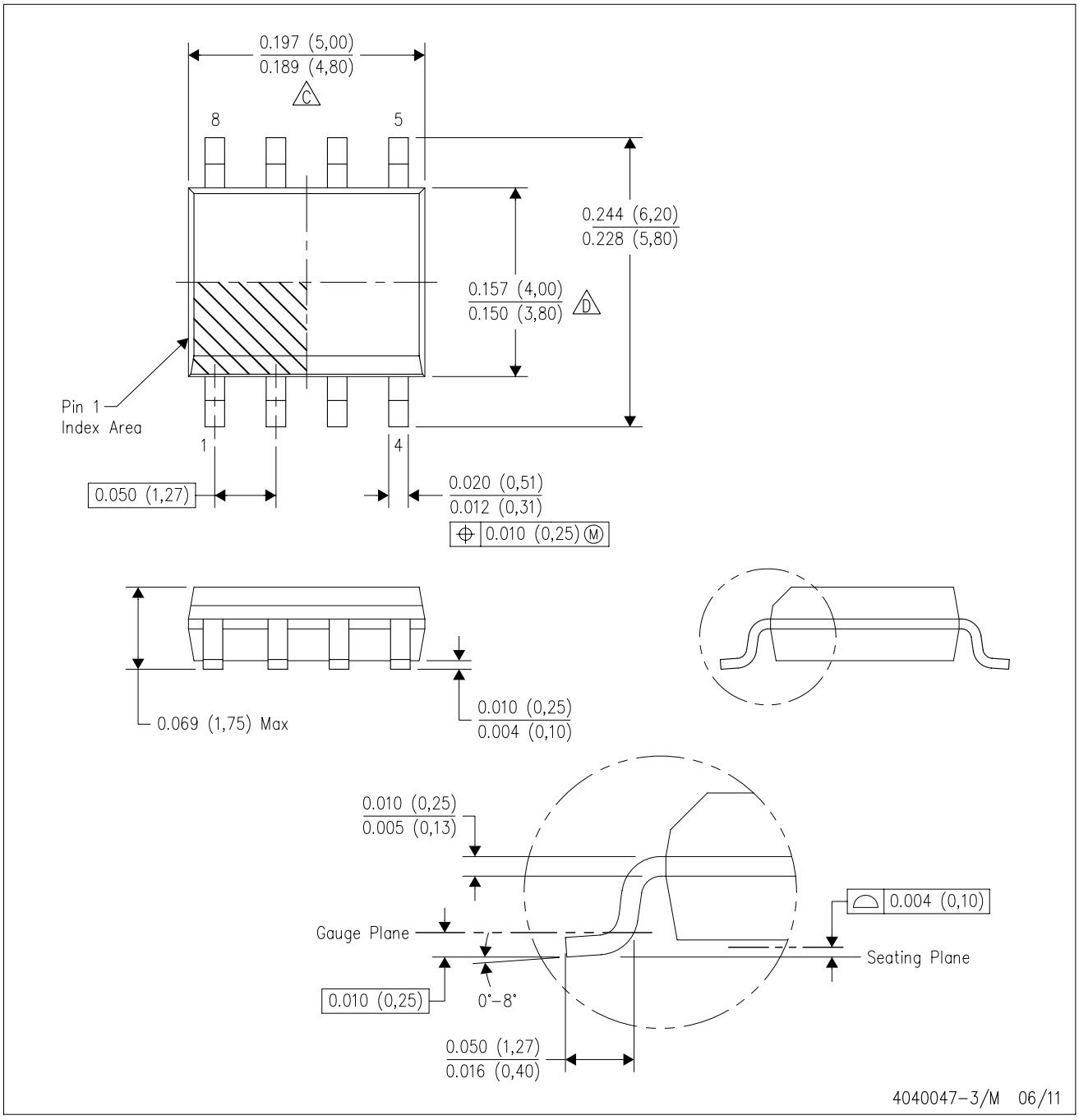
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM9076QBMAX-3.3/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM9076QBMAX-5.0/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

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